

MSB08065G1 650V Silicon Carbide Schottky Diode

Features

-650-Volt Schottky Rectifier

- -Shorter recovery time
- -High-speed switching possible
- -High-Frequency Operation
- -Temperature-Independent Switching Behavior
- -Extremely Fast Switching
- -Positive Temperature Coefficient on VF

Benefits

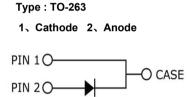
- -Higher safety margin against overvoltage
- -Improved efficiency all load conditions
- -Increased efficiency compared to Silicon Diode alternatives
- -Reduction of Heat Sink Requirements
- -Parallel Devices Without Thermal Runaway
- -Essentialy No Switching Losses

Applications

-Switch Mode Power Supplies -Power Factor Correction -Motor Drives -PD Power -Charging Pile Power -PV Inverterg



Package



Absolute Maximum Ratings T_c = 25°C unless otherwise noted

Symbol	Parameter	MSB08065G1	Units
VRRM	Repetitive Peak Reverse Voltage	650	V
VRSM	Surge Peak Reverse Voltage	650	V
VDC	DC Blocking Voltage	650	V
IF	Continuous Forward Current @Tc=25°C @Tc=135°C @Tc=150°C	27 12 8	A
IFRM	Repetitive Peak Forward Surge Current @TC=25℃ tp = 10 ms, Half Sine Wave	65	А
IFSM	Non-Repetitive Peak Forward Surge Current @TC=25℃ tp= 10 ms, Half Sine Wave	80	А
IFSM	Non-Repetitive Peak Forward Surge Current @TC=25℃, tp= 10 us,pulse	250	A
Ptot	Power Dissipation @Tc=25°C @Tc=110°C	117 51	w
TJ , Tstg	Operating Junction and Storage Temperature	-55 to +175	°C

Ri

Free

Package Marking					
Part Number	Top Marking	Package	Packing Method	MOQ	QTY
MSB08065G1	MSB08065G1	T0-263	Таре	800	4000

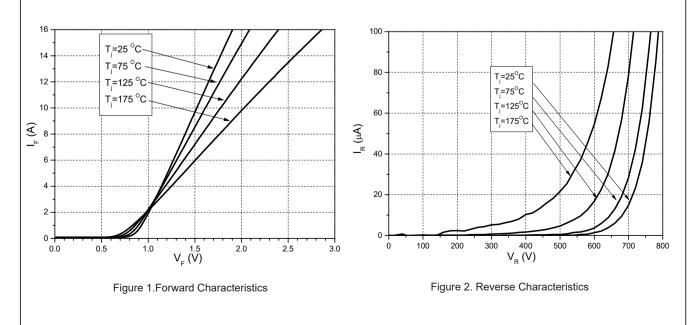
Electrical Characteristics T_c = 25° C unless otherwise noted

Symbol	Test Conditions	Test Conditions	Min	Тур	Max	Unit
VF	Forward Voltage	IF=8A, TC=25°C IF=8A, TC=175°C	-	1.4 1.7	1.8 2.0	V
IR	Reverse Current	VR=650V, TC=25°C VR=650V, TC=175°C	-	5 80	20 200	μΑ
QC	Total Capacitive Charge	VR =400V TJ = 25° C Qc= $\int_0^{v_r} C(V) dv$	-	30	-	nC
с	Total Capacitance	VR =0V, TJ = 25°C, f=1MHz VR =200V, TJ = 25°C, f=1MHz VR =400V, TJ = 25°C, f=1MHz	-	470 40 32	-	pF
EC	Capacitance Stored Energy	VR=400V	-	6.0	-	μJ

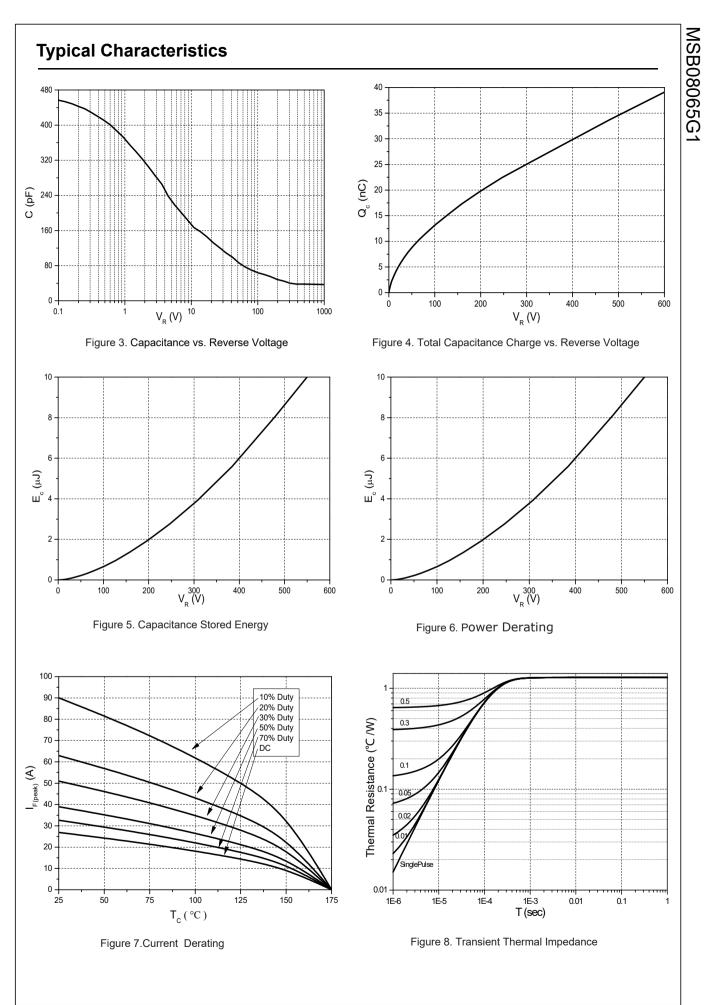
Thermal Characteristics

Symbol	Parameter	Тур	Unit
RθJC	R0JC Thermal Resistance from Junction to Case		°C/W

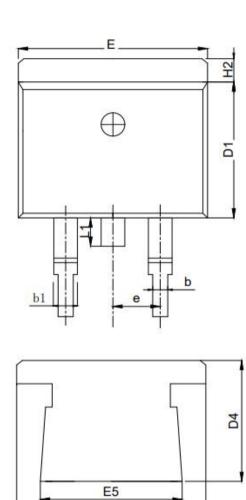
Typical Characteristics

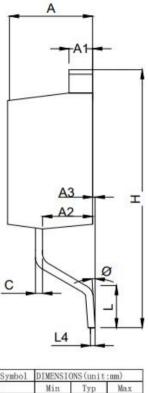


MSB08065G1



TO-263 OUTLINE





Symbol	DIMENSIONS (unit:mm)				
625- 	Min	Тур	Max		
A	4.37	4.57	4.77		
A1	1.22	1.27	1.42		
A2	2.49	2.69	2.89		
A3	0	0.13	0.25		
b	0.7	0.81	0.96		
b1	1.17	1.27	1.47		
с	0.3	0.38	0.53		
D1	8.5	8.7	8.9		
D4	6.6	-	-		
E	9.86	10.16	10, 36		
E5	7.06	-	-		
e	2.54 BSC				
Н	14.7	15.1	15.5		
H2	1.07	1.27	1.47		
L	2	2.3	2.6		
L1	1.4	1.55	1.7		
L4	0.25 BSC				
?	0°	5°	9°		

NOTE:

1The plastic package is not marked as smooth surfaceRa=0.1;Subglossy surfaceRa=0.8 2.Undeclared tolerance \pm 0.25,Unmarked filletRmax=0.25

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